

IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

1. (Currently amended) A method for fabricating a chip-scale package, comprising:  
positioning a preformed polymeric film including at least one aperture that extends substantially longitudinally therethrough over a semiconductor device with the at least one aperture in substantial alignment with a corresponding bond pad of the semiconductor device; and  
selectively introducing conductive material into the at least one aperture following the positioning.
2. (Previously Presented) The method of claim 1, further comprising adhering the preformed polymeric film to the semiconductor device.
3. (Previously Presented) The method of claim 1, further comprising defining at least another aperture through the preformed polymeric film.
4. (Withdrawn) The method of claim 3, wherein defining is effected after positioning.
5. (Previously Presented) The method of claim 3, wherein defining is effected before positioning.
6. (Previously Presented) The method of claim 1, wherein introducing comprises bonding the conductive material to the corresponding bond pad.
7. (Previously Presented) The method of claim 1, wherein introducing comprises depositing the conductive material onto the preformed polymeric film and within the at least one aperture.

8. (Previously Presented) The method of claim 7, wherein depositing comprises chemical vapor depositing or physical vapor depositing the conductive material.

9. (Withdrawn) The method of claim 1, wherein introducing comprises placing a preformed conductive structure within the at least one aperture.

10. (Canceled)

11. (Canceled)

12. (Previously Presented) The method of claim 1, further comprising forming at least one contact at an end of the conductive material, opposite the semiconductor device.

13. (Previously Presented) The method of claim 12, further comprising placing a conductive structure adjacent the at least one contact.

14. (Previously Presented) The method of claim 13, wherein placing comprises applying solder to the at least one contact.

15. (Previously Presented) The method of claim 1, further comprising positioning at least one conductive trace on the preformed polymeric film and in communication with the conductive material.

16. (Previously Presented) The method of claim 15, further comprising forming at least one contact in communication with the conductive trace.

17. (Previously Presented) The method of claim 16, further comprising placing a conductive structure adjacent the at least one contact.

18. (Previously Presented) The method of claim 17, wherein placing comprises applying solder to the at least one contact.
19. (Previously Presented) The method of claim 1, further comprising placing the preformed polymeric film on at least a portion of a peripheral edge of the semiconductor device.
20. (Previously Presented) The method of claim 17, further comprising placing polymeric material at least laterally adjacent the conductive structure.
21. (Original) The method of claim 17, further comprising placing a conductive elastomer over at least one conductive structure.
22. (Previously Presented) The method of claim 21, further comprising placing another conductive structure in contact with the conductive elastomer, opposite the at least one conductive structure.
23. (Withdrawn) A method for fabricating a chip-scale package, comprising: placing photoimageable polymeric material on a surface of a semiconductor device; forming a polymeric film from the photoimageable polymeric material with at least one aperture extending substantially longitudinally through the polymeric film, the at least one aperture aligned with a corresponding bond pad of the semiconductor device; and introducing conductive material into the at least one aperture.
24. (Withdrawn) The method of claim 23, wherein forming comprises selectively exposing regions of the photoimageable polymeric material to electromagnetic radiation.
25. (Withdrawn) The method of claim 23, further comprising defining the at least one aperture through the polymeric film.

26. (Withdrawn) The method of claim 25, wherein defining is effected after the forming.

27. (Withdrawn) The method of claim 25, wherein defining is effected substantially simultaneously with the forming.

28. (Withdrawn) The method of claim 23, further comprising placing at least one conductive trace on the polymeric film and in communication with the conductive material.

29. (Withdrawn) The method of claim 28, further comprising placing at least one contact in communication with the at least one conductive trace.

30. (Withdrawn) The method of claim 29, further comprising placing at least one conductive structure adjacent the at least one contact.

31. (Withdrawn) The method of claim 30, further comprising placing polymeric material at least laterally adjacent the at least one conductive structure.

32. (Withdrawn) The method of claim 30, further comprising placing a conductive elastomer over the at least one conductive structure.

33. (Withdrawn) The method of claim 32, further comprising placing at least one other conductive structure in contact with the conductive elastomer, opposite the at least one conductive structure.

34. (Withdrawn) The method of claim 23, wherein forming comprises forming the polymeric film so as to extend at least partially over a peripheral edge of the semiconductor device.